

Class II change Letter

1、 Explanation of Appearance Differences

The firmware version of the lower layer of the programmable circuit board ASSEMBLY AG0374 is upgraded to AV0027_C→AV0027_D, and change eMMC which causes the version of the upper layer programmable circuit board ASSEMBLY to be upgraded, so the labels are different: AG0374_D→AG0374_E.

2、 Explanation of Circuit Differences

The PCBA label differs due to a firmware version change and eMMC change causing a change in the ASSEMBLY version; otherwise, there are no changes.

3、 Explanation of Functional Differences

Consistent in function

4、 eMMC information between Original and Variant

	Manufacturer	Manufacturer Part Number	Density
Original AG0374_D eMMC information	KIOXIA	THGBMUG6C1LBAIL	8GB
Variant AG0374_E eMMC information	MACRONIX	MX52LM04A11XVW	4GB
	MACRONIX	MX52LM04A11XSI	4GB
	MACRONIX	MX52LM08A11XVW	8GB
	MACRONIX	MX52LM08A11XWI	8GB
The new eMMC chip component is pin-for-pin compatible.			

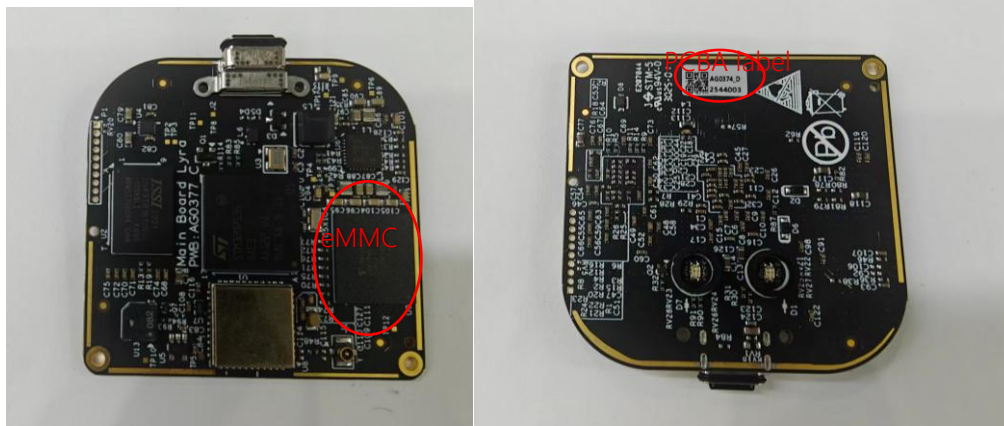
For variant eMMCs, the difference between the models with same densities are working temperatures as following:

MX52LM04A11XVW	32Gbit (4GB)	-25°C ~ +85°C
MX52LM04A11XSI	32Gbit (4GB)	-40°C ~ +85°C
MX52LM08A11XVW	64Gbit (8GB)	-25°C ~ +85°C
MX52LM08A11XWI	64Gbit (8GB)	-40°C ~ +85°C

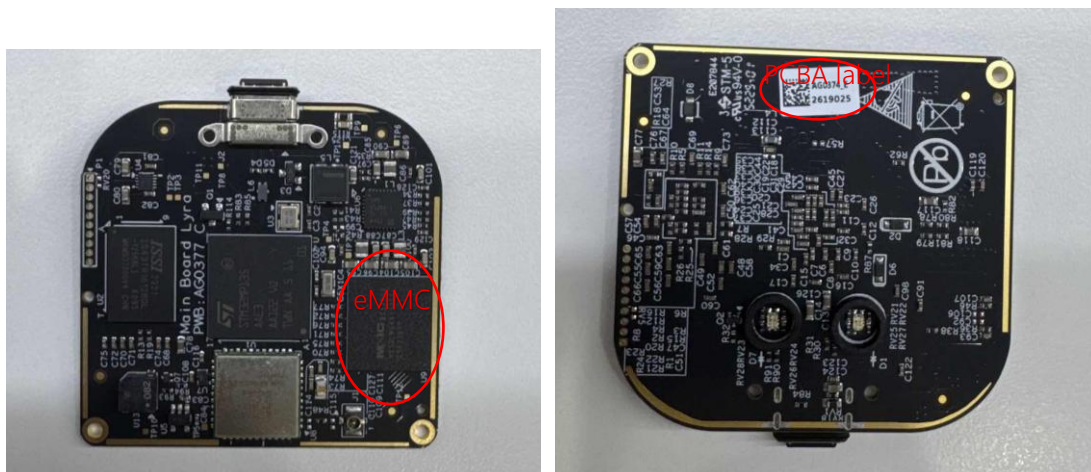
5、Photos

eMMC location and the labels on the circuit board location illustration:

Original display:



Variant display:



Print name: Haoxiang hu

Signature: *Haoxiang Hu*

Company name: Alliedstar Medical Equipment Co., Ltd.